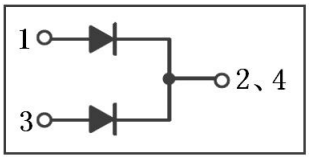
Schottky Barrier Diode in a TO-263 Plastic Package.

Low forward voltage drop,low power losses,High efficiency operation.

For use in high frequency inverters, switching power supplies, freewheeling diodes, OR-ing diode, dc-to-dc converters and reverse battery protection.



PIN1 Anode PIN 2 4 Cathode PIN 3 Anode

See Marking Instructions.

Parameter	Symbol	Rating	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Reverse Voltage	V_{RRM} V_{RWM} V_{DC}	45	V
RMS Reverse Voltage	V_{RMS}	31.5	V
Average forward rectified Current	I_F	2 X 10	A
Non Repetitive Peak Surge Current	I_{FSM}	160	A
Thermal Resistance Junction to Case	R_{Jc}	2.8	/W
Junction and Storage Temperature Range	T_j T_{stg}	-40~+150	

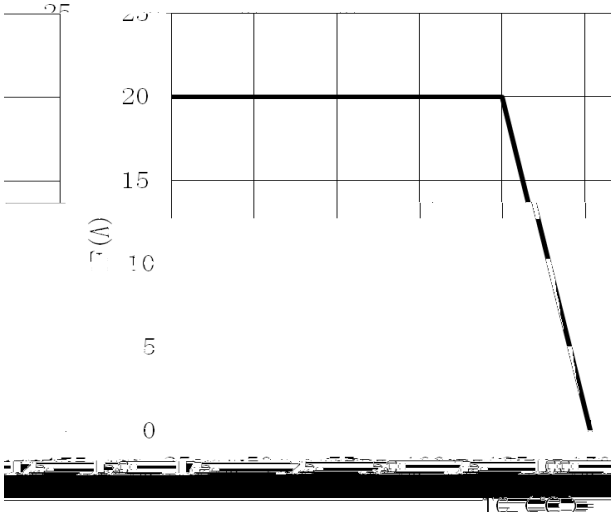
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Reverse Voltage	$V_{(BR)R}$	I_R =1mA Ta=25	45			V
Forward Voltage	V_{FM}	I_F =5.0A Ta=25		0.38		V
		I_F =10A Ta=25		0.43	0.48	V
		I_F =5.0A Ta=125		0.28		V
		I_F =10A Ta=125		0.37	0.45	V
Instantaneous Reverse Current	I_R Note 1	V_R=45V Ta=25		80	200	uA
		V_R=45V Ta=125		30	100	mA

/Notes

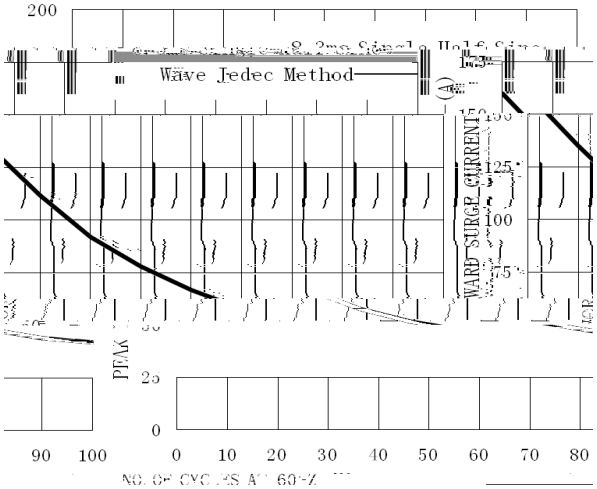
/Short duration pulse test used to minimize self-heating effect.

/ Unless otherwise noted, values for the parameters of a single chip

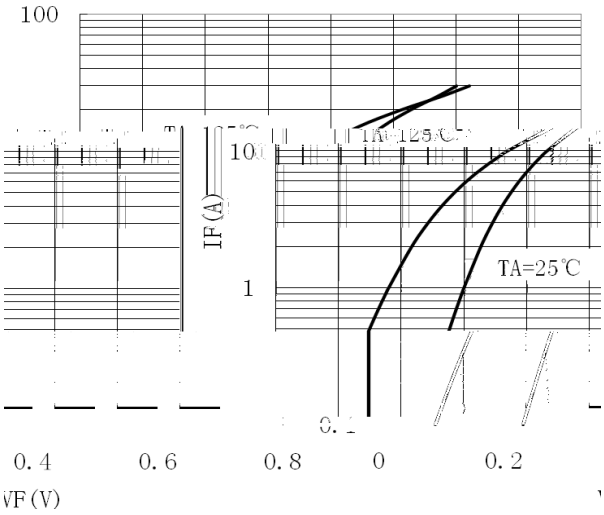
IF – TC



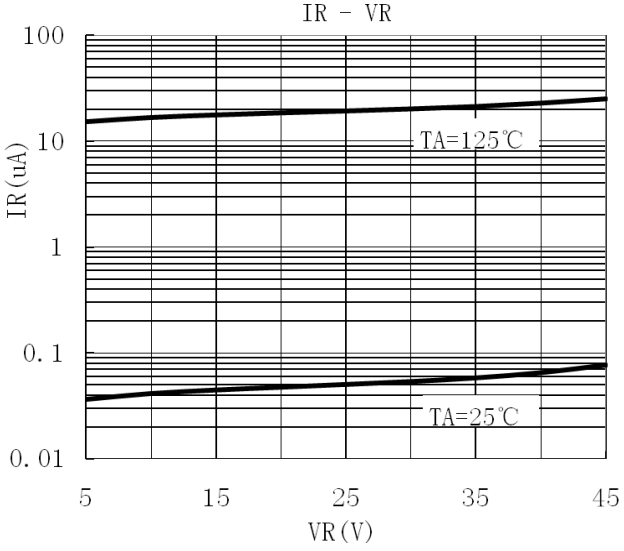
IFSM

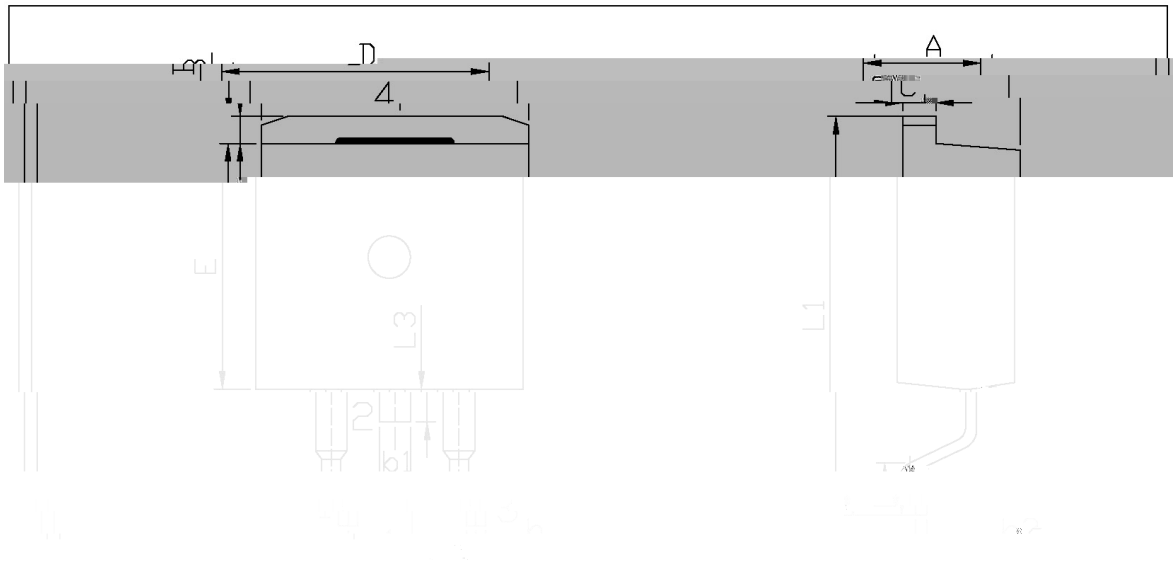


IF – VF



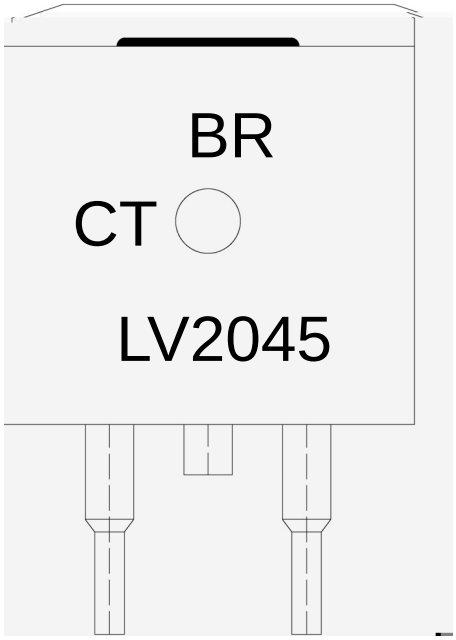
IR – VR





	Min	Max		Min
A	4.30	4.70	E	9.00
B	1.00	1.40	e1	2.34
b1	1.15	1.35	L1	15.(
C	1.20	1.40	L3	1.2
D	9.80	10.20		

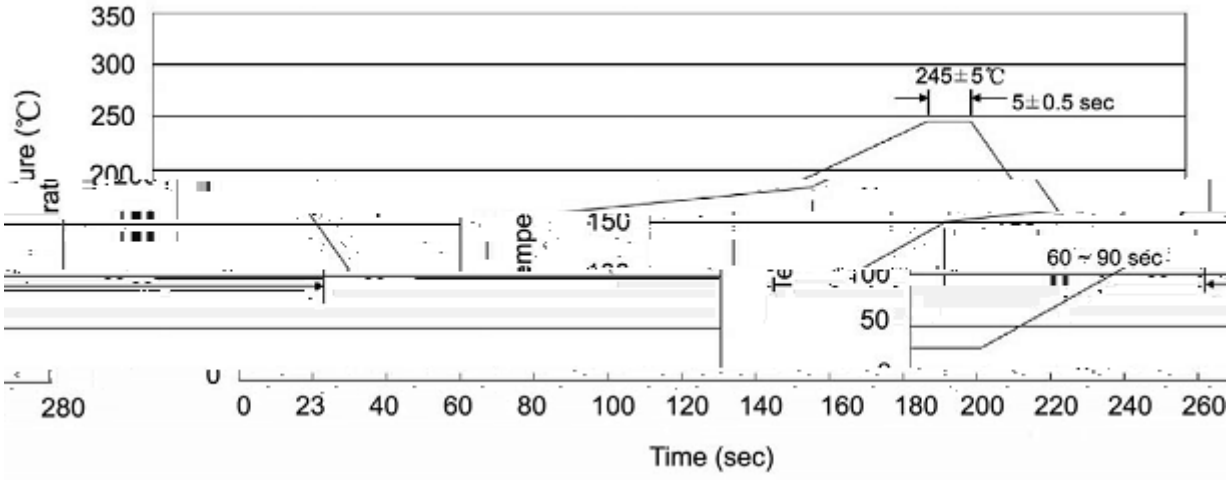
TO-263



Note:

BR:	Company Code
	Product Type.
:	Internal Structure
****:	Lot No. Code, code change with Lot No.

Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

1 25 150 60 90sec;

1.Preheating:25~150 , Time:60~90sec.

2 245 5 5 0.5sec;

2.Peak Temp.:245 5 , Duration:5 0.5sec.

3 2 10 /sec.

3. Cooling Speed: 2~10 /sec.

260 5 10 1 sec. Temp.:260±5 Time:10±1 sec

/ REEL

Package Type	Units					Dimension		(unit mm^3)

/ TUBE

Package Type	Units	Dimension	(unit mm^3)